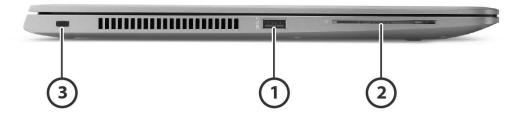
Overview

HP ZBook 15u G5 Mobile Workstation



Front

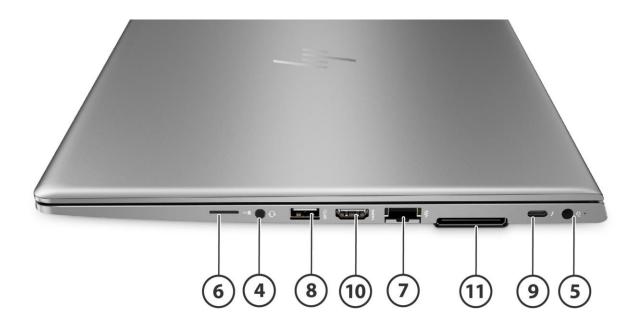
Overview



Left

- 1. 1 USB 3.0 (charging)
- 2. 1 smart card reader
- 3. Security lock slot

Overview



Right

- 4. 1 headphone/microphone combo
- 5. 1 power connector
- 6. 1 UHS-II SD card reader
- 7. 1 Ethernet port (RJ-45)

- 8. 1 USB 3.0
- 9. 1 Thunderbolt 3™
- 10. 1 HDMI port
- 11. Side Docking connector

Overview

At A Glance

- Windows 10 editions, or FreeDOS
- Value performance form factor and thinner industrial design than previous generation workstation grade products.
- Thin & light value performance industrial design, Casted magnesium-reinforced chassis, top cover frame features soft touch paint with lightweight aluminum insert anodized in HP's new "Turbo Silver" color. Backlight keyboard in full aluminum deck with magnesium bottom reinforcement, chemically strengthened glass touchpad, and updated system functions indicators. HP Spill Resistant Collaboration Keyboard with Durakeys, touchpad buttons with Duracoat finish.
- Designed to pass military standard MIL-STD-810G testing*.
- Workstation-caliber AMD Radeon Pro[™] discrete graphics: AMD Radeon Pro[™] WX3100 (2 GB dedicated GDDR5); AMD Enduro[™] graphics technology.
- ISV certified to provide fast and reliable performance with workstation applications, including manipulation of 3D textures
- Choice of 7th or 8th generation Intel[®] Core[™] i7 and i5 processors
- Intel® Core™ i7 with vPro™ and Core™ i5 with vPro™ technology (optional)
- HP Performance Advisor for optimal configuration, compatibility and performance
- Up to two SODIMMs, for system memory up to 32GB
- Supports up to 3 independent displays via internal LCD Panel, system DisplayPort™, system VGA, or using the HP UltraSlim Docking Station or HP Thunderbolt Docking Station. Supports DisplayPort™ 1.2 monitors.
- Bang and Olufsen audio optimized for high fidelity audio with immersive surround sound with deep, rich bass and crystal clear dialog without distortion at high volume
- 3-cell (56 WHr) HP Long Life Battery
- 2 discrete buttons with LED indicator for convenient one touch access: Wireless On/Off, Volume Mute
- Widescreen 15.6-inch diagonal anti-glare LED-backlit display:
- FHD (1920x1080) ultrawide viewing angle, FHD Touch (1920x1080) standard viewing angle. UHD (3840x2160) ultrawide viewing angle
- Supports wireless LAN and wireless WAN options for connectivity on the go.
- One dedicated drive slot. (1) M.2 slots
- Security features including HP Client Security Manager, with central management
- Low halogen, ENERGY STAR® certified and EPEAT® TBD registered in the U.S. EPEAT® status varies by country- please see
 epeat.net.
- HP BIOS self-healing technology including HP Sure Start to prevent, detect, and remedy known and unknown BIOS attacks.

* MIL STD 810G testing is pending and is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

NOTE: See important legal disclosures for all listed specs in their respective features sections.



Features

OPERATING SYSTEM

Preinstalled OS Windows 10 Pro 64*

Windows 10 Home Single Language 64*

FreeDOS 2.0

Supported OS Windows 10 Enterprise 64*

* Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com

NOTE: Your product does not support Windows 8 or Windows 7 In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows® 8 or Windows 7 drivers on http://www.support.hp.com

PROCESSOR*

7th Generation Intel® Core™ i5 7300U (2.6 GHz, 3 MB cache, 2 cores) * Up to 3.5 GHz with Intel® Turbo Boost Technology 7th Generation Intel® Core™ i5 7200U (2.5 GHz, 3 MB cache, 2 cores) * Up to 3.1 GHz with Intel® Turbo Boost Technology 8th Generation Intel® Core™ i7 8650U (1.9 GHz, 8 MB cache, 4 cores) * Up to 4.2 GHz with Intel® Turbo Boost Technology 8th Generation Intel® Core™ i7 8550U (1.8 GHz, 8 MB cache, 4 cores) * Up to 4.0 GHz with Intel® Turbo Boost Technology 8th Generation Intel® Core™ i5 8350U (1.7 GHz, 6 MB cache, 4 cores) * Up to 3.6 GHz with Intel® Turbo Boost Technology 8th Generation Intel® Core™ i5 8250U (1.6 GHz, 6 MB cache, 4 cores) * Up to 3.4 GHz with Intel® Turbo Boost Technology

* Multi-Core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

Also note that the Intel® Turbo Boost is based on max GHz for a single core.



Features

CHIPSET

Chipset integrated with processor

INTEL® CORE™ 15 WITH VPRO/CORE 17 WITH VPRO TECHNOLOGY CAPABLE

Intel® Core™ i5 with vPro™ and Core™ i7 with vPro™ technology is a selectable feature that is available on units configured with select processors, a qualified Intel® Centrino® WLAN module and a preinstalled Windows operating system. It provides advances in remote manageability, security, energy efficient performance, and wireless connectivity. Intel Active Management Technology (iAMT) offers built-in manageability and proactive security for networked mobile workstations, even when they are powered off* or when the operating system is inoperable. It can help identify threats before they reach the network, isolate infected systems, and update mobile workstations regardless of their power state.

* Requires a Windows operating system, network hardware and software, connection with a power source, and a direct (non-VPN) corporate network connection which is either cable or wireless LAN.

NOTE: Some functionality of Intel® Core™ i5 with vPro™/Core™ i7 with vPro™ technology, such as Intel Active Management technology and Intel Virtualization technology, requires additional third- party software in order to run. Availability of future "virtual appliances" applications for Intel® Core™ i5 with vPro™/Core™ i7 with vPro™ technology is dependent on third- party software providers. Compatibility with future "virtual appliances" is yet to be determined.

GRAPHICS

Intel® UHD 620 Graphics*

AMD Radeon Pro™ WX3100 (2 GB dedicated GDDR5) **

Microsoft DirectX 12 (Shader Model 5.0) and OpenGL 4.3capable

AMD Enduro™ Technology supported.

- * HD content required to view HD images
- ** Supports up to 3 independent displays via internal LCD Panel, system DisplayPort™, system VGA, or using the HP UltraSlim Docking Station DisplayPort™ and VGA ports (sold separately).

DISPLAY

Internal

15.6" diagonal LED backlit FHD UWVA eDP anti-glare (1920 x 1080)

15.6" diagonal LED backlit FHD UWVA eDP+PSR anti-glare (1920 x 1080)

15.6" diagonal Touch LED-backlit FHD UWVA eDP (1920 x 1080)

15.6" diagonal Touch LED-backlit FHD UWVA eDP+PSR, anti-glare Privacy (1920 x 1080)

15.6" diagonal LED backlit UHD UWVA eDP+PSR (3840 x 2160)

External

Up to 30-bit (2^30) per pixel "Deep Color" (total of 1,073,741,824 color variations)

DisplayPort™ w/MST (Multi-stream Transport)

Supports resolutions up to UHD 3840 x 2160, 24/30-bit color depth at 60 Hz, and WUXGA (1920 x 1200) monitors, with 24/30-bit color depth up to 120 Hz.



Features

DisplayPort™ Features

Multi-stream Transport (MST): Multi-stream Transport is a DisplayPort™ 1.2 feature that allows daisy chaining of DisplayPort™ 1.2 monitors (requires monitor with DisplayPort™ 1.2 MST capability), or the use of DisplayPort™ 1.2 hubs with MST to achieve a maximum of 3 active displays.

DVI-D (single link)

DVI support requires a DP-to-DVI adapter (sold separately). Dual-Link DVI is supported with an active USB powered adapter (sold separately).

NOTE: Resolutions are dependent upon monitor capability, and resolution and color depth settings.

STORAGE AND DRIVES

Primary Storage Bay

M.2 SATA SED SSD

512GB SATA-3 SS TLC SSD FIPS-140-2

HP Z Turbo Drive (NVMe PCIe SSD)

256GB PCIe Gen3x4 (NVMe) TLC Solid State Drive 512GB PCIe Gen3x4 (NVMe) TLC Solid State Drive 1TB PCIe Gen3x4 (NVMe) TLC Solid State Drive 256GB PCIe Gen3x4 (NVMe) TLC Solid State Drive Opal 2 512GB PCIe Gen3x4 (NVMe) TLC Solid State Drive Opal 2 256GB PCIe Gen3x4 (NVMe) MLC Solid State Drive 512GB PCIe Gen3x4 (NVMe) MLC Solid State Drive 1TB PCIe Gen3x4 (NVMe) MLC Solid State Drive

HP 3D DriveGuard (Windows only)

The hard drive is mounted directly to the notebook frame, reducing the transmission of shock to the hard drive.

* For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to up to 30 GB (for Windows 10) disk is reserved for system recovery software.



Features

DRIVE CONTROLLERS

M.2 Storage Bay (SATA-3 for HDD and SATA-3 for SSD

HP Z Turbo Drive: PCIe NVMe SSD RAID: Not supported

NOTE: Raid 0, 1 supported only on SATA drives.

MEMORY

Standard

32 GB DDR4 1.2V Non ECC SDRAM (Transfer rates up to 2400MT/s)
Two SODIMM slots supporting dual-channel memory
4 GB, 8GB and 16 GB SODIMMs

Maximum

Upgradeable to 32768 MB with optional 16384 MB SODIMMs in 2 slots

Dual-channel

Maximized dual-channel performance requires SODIMMs of the same size and speed in both memory channels.

* Maximum memory capacities assume Windows 64-bit operating systems or Linux. With Windows 32-bit operating systems, memory above 3 GB may not all be available due to system resource requirements.

NOTE: Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

NETWORKING/COMMUNICATIONS

Communications

Intel® I219-LM Gigabit* Network Connection (vPro configurations)
Intel® I219-V Gigabit* Network Connection (non-vPro configurations)

* The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

Wireless

Secure, integrated wireless LAN and wireless WAN options featuring support for the latest industry standards. Broadband Wireless (WWAN) requires a Windows operating system and is available in select countries as a standard, factory configurable feature only. Integrated Bluetooth is also available (factory configurable only) combined with the supported wireless LAN option.

802.11 Wireless LAN*

Intel® Dual Band Wireless-AC 8265 802.11 a/b/g/n/ac (2x2) WiFi + Bluetooth 4.2 Combo Adaptor* (vPro) Intel® Dual Band Wireless-AC 8265 802.11 a/b/g/n/ac (2x2) WiFi + Bluetooth 4.2 Combo Adaptor* (non-vPro)

Wireless WAN - Mobile Broadband **



Features

HP lt4120 Qualcomm® Snapdragon™ X5 LTE Mobile Broadband Module (optional) HP lt4132, LTE/HSPA+ 4G Mobile Broadband Module (optional) HP hs3210 HSPA+ Mobile Broadband Module (optional)

Near Field Communications (NFC)

HP Module with NXP NFC Controller NPC100

* Wireless cards are optional or add-on features and requires separately purchased wireless access point and internet service. Availability of public wireless access points limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices.

** WWAN use requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, and in all regions.

AUDIO/MULTIMEDIA

Audio

Bang and Olufsen audio
Integrated stereo speakers
Integrated microphone (dual-microphone array when equipped with optional webcam)
Button for volume mute; function keys for volume up and down
Combo mic-in / stereo headphone-out jack

Webcam

720 HD webcam with IR (Near infrared imaging - optional)

- Microsoft Hello Certification: Microsoft face authentication in Windows 10 is an enterprise-grade identity verification mechanism
- Microsoft Skype for Business1 Certified
- HD format (widescreen 16:9)
- Supports videoconferencing and still image capture
- · High quality fixed focus lens
- · Video capture at various resolutions up to 1280x720 resolution (720p) and up to 30fps
- M-JPEG compression supports higher frame rates for video capture and videoconferencing
- · Improved low light sensitivity
- Improved dynamic range
- * HD content required to view HD images.

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Kevboard

Optional backlit keyboard with Function key control to toggle backlit brightness setting - off/full/half brightness The HP spill-resistant keyboard is designed using a thin layer of Mylar film under the keyboard and a drain system that funnels fluid through a hole in the bottom of the notebook. This minimizes the risk of damage to sensitive components underneath. The 102-key compatible keyboard features a full-pitch key layout with desktop keyboard features, such as editing keys, both left and right control and alt keys, function keys, and 18.0 x 18.4 mm key pitch (center-to-center spacing). U.S. and International key layouts are available. Other features include hot keys for instant access to power conservation and brightness.



Features

Pointing Devices

Point stick with two additional point stick buttons

Image sensor Clickpad for enhanced performance and improved precision on scroll and gesture

Function Keys

Function keys provide control of the following features: standby mode, external display, volume down, volume up HP Power Assistant (Windows® 7 only), and display brightness.

- F1 Display Switching
- F2 Blank or SureView
- F3 Brightness Down
- F4 Brightness Up
- F5 Audio Mute
- F6 Volume Down
- F7 Volume Up
- F8 Mic Mute
- F9 Backlit Toggle
- F10 Numlk
- F11 Wireless
- F12 Calendar
- >Share/Present
- >Call Answer
- >Call End

SOFTWARE AND SECURITY

Preinstalled Software with Windows Operating System

BIOS

HP BIOSphere Gen31

HP Sure Start Gen3²

HP DriveLock | HP Automatic DriveLock

BIOS Update via Network

Master Boot Record Security

Power On Authentication

Secure Erase³

Absolute Persistence Module⁴

Pre-boot Authentication

Multi Media

Cyberlink Power MediaPlayer CMIT

Communication / Connectivity

HP Mobile Connect Pro5

Native Miracast Support⁶

HP LAN-WLAN Protection

HP MAC Address Manager (select models only)

HP Wireless Wakeup (select models only)

HP SureConnect

HP Value Add Software

HP 3D DriveGuard 6

HP ePrint Driver + JetAdvantage7



Features

HP Hotkey Support

HP Recovery Manager

HP Jumpstart

HP Support Assistant¹²

HP Noise Cancellation Software

HP Performance Advisor

HP Remote Graphics Software

HP Velocity

Microsoft Products

Buy Office Bing Search Skype⁸

Manageability

HP Driver Packs 9

HP SoftPaq Download Manager (SDM)

HP System Software Manager (SSM) 9

HP BIOS Config Utility (BCU) 9

HP Client Catalog 9

HP Manageability Integration Kit for Microsoft SCCM 10

HP Image Assistant

LANDESK Management 11

For more information on HP Client Management Solutions refer to: http://www.hp.com/go/clientmanagement.

Client Security Software

- HP Client Security Suite Gen3¹³
- HP Security Manager (including Credential Manager and Password Manager)
- HP Fingerprint Sensor
- Power On Authentication
- Device Access Manager
- Microsoft Defender 14
- HP WorkWise¹⁵

Standard

For Windows 10, Trusted Platform Module (TPM) 2.0 (Infineon SLB9670). Common Criteria EAL4+ Certified. HP Fingerprint Reader

For more information on HP Client Security Software Suite, refer to http://www.hp.com/go/clientsecurity.

- 1. Requires Intel® 7th generation processors
- 2. Available on HP Elite and Z products equipped with Intel® 7th generation processors.
- 3. For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88. Supported on Elite and Z platforms with BIOS version F.03 or higher
- 4. Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: http://www.absolute.com/company/legal/agreements/ computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.
- 5. HP Mobile Connect Pro is only available on preconfigured devices with WWAN. For geographic availability refer to http://www.hp.com/go/mobileconnect



Features

- 6. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming media players that also support Miracast. You can use Miracast to share what you're doing on your PC and present a slide show. For more information: http://windows.microsoft.com/en-us/windows-8/project-wireless-screen-miracast
- 7. Requires an Internet connection to HP web-enabled printer and HP ePrint account registration (for a list of eligible printers, supported documents and image types and other HP ePrint details, see http://www.hp.com/go/eprintcenter). Separately purchased data plans or usage fees may apply. Print times and connection speeds may vary.
- 8. Skype is not offered in China.
- 9. Not preinstalled, however available for download at http://www.hp.com/go/clientmanagement
- 10. HP Manageability Integration Kit can be downloaded from http://www8.hp.com/us/en/ads/clientmanagement/overview.html
- 11. Subscription required.
- 12. Requires Windows and Internet Access
- 13. Requires Windows and Intel® 7th generation processors.
- 14. Opt in and internet connection required for updates.
- 15. HP WorkWise smartphone app is available as a free download on the App Store and Google Play. As of September 2017, HP WorkWise will no longer support iOS or iPhone® devices.

Workstation ISV Certifications

Find the latest list of certifications at: http://www.hp.com/go/isv

HP Remote Graphics Software

The remote desktop solution for serious workstation users and their most demanding applications.

Download at: http://www.hp.com/go/RGS

HP Performance Advisor

Get the most out of your HP Workstation on day one—and every day thereafter. Designed for all users regardless of technical background, this ultra-savvy software wizard is the simplest and most effective way to make sure your computer is always operating at its optimum potential.

Download at: http://www.hp.com/go/performanceadvisor

Security

See Software section above.

Other Standard Security Features

Integrated Smart Card Reader One-Step Logon Security lock slot Support for Intel® AT

Optional Security Features

HP Fingerprint Sensor (optional)

Absolute Data Protect* with GPS Tracking - Subscription based security solution providing the ability to track, initiate physical recovery, conduct asset management, and perform remote data delete by utilizing GPS technology. GPS functionality requires HP Mobile Broadband Module.

* The Absolute Data Protect agent is shipped turned off, and must be activated by customers when they purchase a subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S.

HP CENTRAL MANAGEMENT



Features

HP offers a variety of scalable hardware, software, and BIOS-based security features to help you defend your organization against viruses and other threats. These integrated security features safeguard what matters to you the most - your data, device and identity. Now, be confident your fleet of devices is protected in multiple layers of HP Client Security protection.

HP BIOS Protection keeps you up and running with enhanced protection against virus attacks and other threats. And if the BIOS is accidently compromised, the auto recovery feature automatically restores it to its fully functional state.

HP Sure Start detects and negates a BIOS attack with automatic recovery of the BIOS even when the installation is accidentally compromised (i.e. power outage). When HP Sure Start heals the BIOS an event log is generated that an IT administrator can retrieve so the business is aware of a BIOS attack. Golden copy of BIOS is stored in protected nonvolatile memory providing redundant, hardware-based protection against a new generation of attacks.

An optional fingerprint reader and integrated Smart Card Reader help keep your identity secure. The security cable slot helps keep your notebook physically secure.

You can even permanently destroy data on your hard drive in preparation for your system disposal or redeployment with Secure Erase.



Features

POWER

Power Supply

HP 65W Slim Smart AC Adapter

Primary Battery

HP 3-cell Long Life Polymer Battery (56 WHr)

Battery Life

Battery life up to 10 hours *

NOTE: Battery is internal and not replaceable by the customer

System Standby Time

Up to TBD weeks**

*Battery life will vary depending on the product model, configuration, loaded applications, features, use, wireless functionality and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See MobileMark14 battery benchmark https://bapco.com/products/mobilemark-2014/ for additional details.
** Standby life will vary depending on various factors including battery, Memory, CPU, EC and LAN chip. The maximum capacity of the battery will naturally decrease with time and usage.

Power Conservation

AMD® Polaris™ Technology Hibernation Standby ACPI compliance

ENVIRONMENTAL

US ENERGY STAR®
IT ECO declaration

EPEAT® registered where applicable. EPEAT® registration varies by country. See http://www.epeat.net for registration status by country. See HP's 3rd party option store for solar energy accessory www.hp.com/qo/options.

NOTE: This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks.

WEIGHTS & DIMENSIONS

Weight

Starting at 3.89 lb (1.77 kg)

Dimensions (w x d x h) 14.6 x 9.91 x 0.72 in 370.8 x 251 x 18.6 mm

NOTE: Height varies depending upon where on the notebook the measurement is made. Weight varies by configuration and components. Weight includes 3 cell 46Whr battery, without hard drive and with 256 GB Z Turbo Drive (PCIe SSD).



Features

PORTS/SLOTS

Ports

Left side:

- (1) USB 3.0 Charging Port
- (1) Security lock slot

Right side:

- (1) Thunderbolt 3™
- (1) USB 3.0 Port
- (1) Headphone/Microphone Combo
- (1) RJ-45 / Ethernet
- (1) Side Docking connector
- (1) Power connector

Digital Media Slots

- (1) SD UHS-II Flash Media slot Supports next generation SD (Secure Digital), backward compatible to SDHC, SDXC
- (1) Integrated Smart Card Reader (Compatible with ISO 7816 compliant Smart Cards PC/SC interface support)

SERVICE AND SUPPORT

Limited 3-year or 1-year limited warranty options available, depending on country. Batteries have the same 1-year or 3-year limited warranty as the platform. Optional¹ HP Care Pack Services are extended service contracts which go beyond your standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at http://www.hp.com/go/cpc.

Sold separately or as an optional feature. Service levels and response times for HP Care Packs may vary depending
on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. HP
services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the
time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights
are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your
HP Product. Consult your local HP Customer Support Center for details.



Technical Specifications – System Unit

SYSTEM UNIT

Stand-Alone Power **Nominal Operating** 19.5 V dc @ 3.3 A Requirements (AC Power) Voltage

Average Operating Power Windows® 10 (64-bit)

AMD FirePro™ Graphics

Max Operating Power < 65 W

Temperature Operating 32° to 95° F (0° to 35° C) (not writing optical)

41° to 95° F (5° to 35° C) (writing optical)

Non-operating -4° to 140° F (-20° to 60° C)

Relative Humidity Operating 10% to 90%, non-condensing

> 5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature Non-operating

Shock Operating 40 G, 2 ms, half-sine

200 G, 2 ms, half-sine Non-operating

Random Vibration Operating 0.75 grms

Non-operating 1.50 grms

Altitude (unpressurized) **Operating** -50 to 10,000 ft. (-15.24 to 3,048 m)

> Non-operating -50 to 15,000 ft. (-15.24 to 12,192 m)

Planned Industry Standard Certifications

UL Yes **CSA** Yes **FCC Compliance** Yes

ENERGY STAR® Select models* **EPEAT®** Gold target**

ICES Yes Australia / Yes **NZ A-Tick Compliance**

Yes **Japan VCCI Compliance** Yes KCC Yes **BSMI** Yes **CE Marking Compliance** Yes MIL STD*** **Planned**

For accessibility information on HP products, please visit: http://www.hp.com/accessibility.



^{*} Configurations of the HP ZBook 15u G5 that are ENERGY STAR® certified are identified as HP ZBook 15u G5 ENERGY STAR® on HP websites and on http://www.energystar.gov.

^{**} EPEAT registration varies by country. See http://www.epeat.net for registration status by country. EPEAT status listed above applies to U.S.

^{***} MIL STD 810G testing is pending and is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Damage under the MIL STD test conditions or any accidental damage requires an optional HP Accidental Damage Protection Care Pack.

Technical Specifications – Displays

DISPLAYS

14.0" diagonal LED backlight FHD UWVA IPS eDP Anti-glare (1920 x 1080) **Dimensions** (W x H) 315.41 x 196.17 max. (w/ PCB)

Active Area 309.37 x 174.02 (mm)

Weight 225g max
Surface Treatment Anti-glare
Contrast Ratio 600:1 (typical)

Refresh Rate 60 Hz

Brightness 340 nits

Pixel Resolution Format 1920 x 1080 (FHD)

Configuration RGB

Backlight LED **PPI** 157

Viewing Angle UWVA 85/85/85

14.0" diagonal LED backlight FHD SVA eDP Anti-glare (1920 x 1080) **Outline Dimensions** (W x H x D)

ensions 320.9 x 205.6 x 3 (mm) max

Active Area 309.40 x 173.95 (mm)

Weight 270 g max

Diagonal Size 14.0 (inch)

Surface Treatment Anti-Glare (AG)

Contrast Ratio 300:1 (typical)

Refresh Rate 60 Hz **Brightness** 300 nits

Format 1920 x 1080 (FHD)
Pixel Resolution

Configuration RGB

Interface eDP 1.2 **PPI** 157

Viewing Angle SVA 45/45/25/35

14.0" diagonal LED backlight FHD SVA eDP (1920 x 1080) Touch with Camera **Outline Dimensions**

 $(W \times H \times D)$

320.9 x 205.6 x 3 (mm) max

Active Area 309.40 x 173.95 (mm)

Weight 270 g max Diagonal Size 14.0 (inch)

Surface Treatment Anti-smudge/fingerprint coating

Contrast Ratio 300:1 (typical)

Touch Enabled Yes

TSP Type Capacitive
Refresh Rate 60 Hz
Brightness 300 nits

Pixel Resolution Format 1920 x 1080 (FHD)

Technical Specifications – Displays

		Configuration	RGB
	Interface	eDP 1.2	
	LCD Mode	TN	
	PPI	157	
14.0" diagonal LED backlight HD SVA eDP (1366 x 768)	Viewing Angle	SVA 45/45/25/35	
	Active Area (W x H)	309.4 x 173.95 (mm)	
	Dimensions (W x H)	320.9 x 205.6 (mm) max	
	Weight	290 g max	
	Surface Treatment	Anti-Glare (AG)	
	Contrast Ratio	300:1 (typ)	
	Refresh Rate	60 Hz	
	Brightness	220 nits	
	Pixel Resolution	Format	1920 x 1080 (FHD)
		Configuration	RGB
	Backlight	LED	
	PPI	112	
	Viewing Angle	SVA 45/45/25/35	



Technical Specifications – Storage

STORAGE AND DRIVES*

500 GB 5400rpm Self Encrypting Drive (FIPS-140-2) (Opal 2)

 Drive Weight
 0.21 lbs (95 g)

 Capacity
 500 GB

 Height
 0.28 in (7 mm)

 Width
 2.75 in (69.85 mm)

 Interface
 ATA-8, SATA 3.0

Transfer Rate Synchronous (maximum) 600 MB/s

Seek Time Single Track 1.5 ms 12 ms

typical reads, including settling) Maximum 21 ms

CacheUp to 32MBRotational Speed7200 rpmLogical Blocks976,773,168

Operating Temperature 32° to 140° F (0° to 60° C) [top cover temp]

Features ATA Security; TCG Opal 2.x, FIPS, S.M.A.R.T., NCQ, Ultra DMA

500 GB 7200rpm Hard Drive **Drive Weight** 0.20 lbs (92 g) ~ 0.21 lbs (95 g)

 Capacity
 500 GB

 Height
 0.28 in (7 mm)

 Width
 2.75 in (69.85 mm)

 Interface
 ATA-8, SATA 3.0

Transfer Rate Synchronous (maximum) 1.5 ms ~ 2.0 ms

Seek Time Single Track 11 ms ~ 13 ms
(typical reads, including settling) 1.5 ms ~ 22 ms

Maximum 1.5 ms ~ 2.0 ms

CacheUp to 32 MBRotational Speed7200 rpmLogical Blocks976,773,168

Operating Temperature 32° to 140° F (0° to 60° C) [case temp] **Features** ATA Security, S.M.A.R.T., NCQ, Ultra DMA

500 GB 7200rpm Self-Encrypting Drive (Opal 2)

 Drive Weight
 0.21 lbs (95 g)

 Capacity
 500 GB

 Height
 0.28 in (7 mm)

 Width
 2.75 in (69.85 mm)

 Interface
 ATA-8, SATA 3.0

Transfer Rate Synchronous (maximum) 600 MB/s

Seek Time Single Track 1.5 ms
(typical reads, including settling) Average 12 ms

Maximum 21 ms

CacheUp to 32MBRotational Speed7200rpmLogical Blocks976,773,168

Operating Temperature 32° to 140° F (0° to 60° C) [top cover temp]

Features ATA Security; TCG Opal 2.x, S.M.A.R.T., NCQ, Ultra DMA

1 TB 5400rpm Hard Drive Drive Weight 0.21 lbs (94 q)- 0.21 lbs (95 q)

12 ms-13 ms

QuickSpecs

Technical Specifications – Storage

Capacity 1 TB

 Height
 0.28 in (7 mm)

 Width
 2.75 in (69.85 mm)

 Interface
 ATA-8, SATA 3.0

Transfer RateSynchronous (maximum)600 MB/sSeek TimeSingle Track2 ms

Average

(typical reads, including settling)

Maximum 18 ms-22 ms

Cache Up to 32MB

Rotational Speed 5400 rpm

Logical Blocks 1,953,525,168

Operating Temperature32° to 140° F (0° to 60° C) [case temp]FeaturesATA Security, S.M.A.R.T., NCQ, Ultra DMA

Drive Weight 0.198 lbs (90 g) ~ 0.20 lbs (92 g)

Capacity 500 GB Height 0.28 in (7 mm)

 Width
 2.75 in (69.85 mm)

 Interface
 ATA-8, SATA 3.0

Transfer Rate Synchronous (maximum) 600 MB/s

Seek Time Single Track 1.5 ms ~ 2 ms (typical reads, including settling)

Average 12 ms ~ 13 ms 22 ms ~ 32 ms

CacheUp to 128MBRotational Speed5400 rpmLogical Blocks976,773,168

Operating Temperature 32° to 140° F (0° to 60° C) [case temp] **Features** ATA Security, S.M.A.R.T., NCQ, Ultra DMA

256 GB M2 2280 SATA-3 Self-Encrypting Drive (Opal 2) TLC Solid State Drive

500 GB Hybrid,

8 GB cache

 Drive Weight
 0.02 lb (10 g)

 Capacity
 256 GB

 Height
 0.09 in (2.23 mm)

 Width
 0.87 in (22 mm)

 Interface
 ATA-8, SATA 3.0

Performance Maximum Sequential Maximum Sequential Write

Read

Up to 530 MB/s Up to 515 MB/s

Logical Blocks 500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TCG Opal 2.0, DIPM; TRIM; DEVSLP

HP Z Turbo Drive 512 GB, Drive Weight 0.022 lb (10 g)
M.2 NVMe MLC Solid Capacity 512 GB

Height 0.09 in (2.3 mm)
Width 0.87 in (22 mm)

NAND Type MLC

Form-Factor (I/O) M.2 2280



State Drive

Technical Specifications – Storage

Interface PCIe NVMe Gen3X4

Performance Maximum Sequential Maximum Sequential Write

Read

Up to 3000 MB/s Up to 1500MB/s

Logical Blocks 1,000,215,216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security (option), TRIM; L1.2

HP Z Turbo Drive 1 TB, M.2 NVMe MLC Solid State Drive
 Drive Weight
 0.02 lb (10 g)

 Capacity
 1024 GB

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

NAND Type MLC Form-Factor (I/O) M.2 2280

InterfacePCIe NVMe Gen3X4Drive Weight0.02 lb (10 g)

Performance Maximum Sequential Maximum Sequential Write

Read

Up to 3,000 MB/s Up to 2,900 MB/s

Logical Blocks 2,000,409,264

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security (Option), TRIM; L1.2

HP Z Turbo Drive 256 GB, Drive Weight
M.2 NVMe MLC Solid Capacity
State Drive Height

 Drive Weight
 0.02 lb (10 g)

 Capacity
 256 GB

 Height
 0.09 in (2.23 mm)

 Width
 0.87 in (22 mm)

NAND Type MLC Form-Factor (I/O) M.2 2280

Interface PCIe NVMe Gen3X4

Performance Maximum Sequential Maximum Sequential Write

Read

Logical Blocks 500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security (Option);TRIM; L1.2



Technical Specifications – Storage

HP Z Turbo Drive 256 GB, Drive Weight M.2 NVMe TLC Solid State Capacity Drive

 Drive Weight
 0.02 lb (10 g)

 Capacity
 256 GB

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

NAND Type TLC Form-Factor (I/O) M.2 2280

Interface PCIe NVMe Gen3X4

Performance Maximum Sequential Maximum Sequential Write

Read

Up to 2,600 MB/s Up to 900 MB/s

Logical Blocks 500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security (Option); TRIM; L1.2

HP Z Turbo Drive 512 GB, Drive Weight
M.2 NVMe TLC Opal 2
Capacity
Solid State Drive

 Drive Weight
 0.02 lb (10 g)

 Capacity
 512 GB

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 NAND Type
 M.2 2280

Form-Factor (I/O) PCIe NVMe Gen3X4
Interface 0.02 lb (10 q)

Performance Maximum Sequential Maximum Sequential Write

Read

Up to 2,600 MB/s Up to 1,400 MB/s

Logical Blocks 1,000,215,216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security (Option);TRIM; L1.2

HP Z Turbo Drive 512 GB, M.2 SATA TLC FIPS Solid State Drive

 Drive Weight
 0.02 lb (10 g)

 Capacity
 512 GB

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

Generation

NAND Type TLC
Form-Factor (I/O) M.2 2280
Interface ACS-3, SATA 3.2

Performance Maximum Sequential Maximum Sequential Write

Read

Up to 530 MB/s Up to 400 MB/s

Logical Blocks 1,000,215,216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TCG Opal 2.0; FIPS; DIPM; TRIM; DEVSLP

Technical Specifications – Storage

* For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to up to 30 GB (for Windows 10) disk is reserved for system recovery software.



200*1 (plus another secondary line); 508 dpi, sensor area 12*3 mm

QuickSpecs

Technical Specifications – Security

SECURITY

HP Fingerprint Sensor Voltage 3.0-3.6V

Operating temperature 14° - 167°F (-10° - 75°C)

Current consumption image 36mA **Low latency wait for finger** 950 uA

Capture rate 3000 lines/sec

ESD Resistance IEC 6100-4-2 4B (+/-15KV)

Detection Matrix 200*1 (plus another secondal



Technical Specifications – Networking

NETWORKING/COMMUNICATION

Intel® I219-LM Gigabit Network Connection (vPro configurations) Ethernet Features 10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-

14)

100 10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses

13-14)

100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses

21-30

1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023.

Clauses 40)

Auto-Negotiation (Automatic Speed Selection)

Full Duplex Operation at all Speeds, Half Duplex operation at 10 and

100 Mbit/s

IEEE 802.1p QoS (Quality of Service) Support

IEEE 802.1q VLAN support

IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)

IEEE 802.3az EEE(Energy Efficient Ethernet)

Jumbo Frame 9K

Auto MDI/MDIX Crossover cable detection ACPI compliant - multiple power modes

PowerACPI compliant - multiple power modesManagementEnergy Detect Low Power Mode(Green Ethernet)PerformanceTCP/IP/UDP Checksum Offload (configurable)

Features Protocol Offload(ARP & NS)

Large send offload and Giant send offload

Receiving Side Scaling MACSec Offload (802.3ae)

Intel® vPro iSCSI Boot

RSS is kernel based support (e.g. in Win Server 2013)

Ultra Low Power at cable disconnect (<1mW) enables platform

support for connected standby.

Manageability Wake-on-LAN from standby and hibernation (Magic Packet and

Microsoft Wake-Up Frame): Wake-on-LAN from off (Magic Packet

only)

PXE 2.1 Remote Boot

Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB

(802.3x, clause 30))

 $Comprehensive\ diagnostic\ and\ configuration\ software\ suite$

Virtual Cable Doctor for Ethernet cable status

Interface PCI Express 1.1 x1 to fully support ASPM LOs/L1 and CLKREQ.

NOTE: Intel® I219-LM Gigabit interface is not PCIe compliant. It operates at half of PCIe specification V1.1 (2.5GT/S) speed.

NIC Device Driver Name Intel® Ethernet Network Connection I219-LM

Technical Specifications – Networking

Intel® 1219-V Gigabit Network Connection (Non-vPro configurations) Ethernet Features 10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses

13-14)

100 10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3

clauses 13-14)

100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3

clauses 21-30)

1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023.

Clauses 40)

Auto-Negotiation (Automatic Speed Selection)

Full Duplex Operation at all Speeds, Half Duplex operation at 10

and 100 Mbit/s

IEEE 802.1p QoS (Quality of Service) Support

IEEE 802.1q VLAN support

IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)

IEEE 802.3az EEE(Energy Efficient Ethernet)

Jumbo Frame 9K

Auto MDI/MDIX Crossover cable detection

Power ACPI compliant - multiple power modes

ManagementEnergy Detect Low Power Mode(Green Ethernet)PerformanceTCP/IP/UDP Checksum Offload (configurable)

Features Protocol Offload(ARP & NS)

Large send offload and Giant send offload

Receiving Side Scaling MACSec Offload (802.3ae)

Intel Non-vPro iSCSI Boot

Manageability Wake-on-LAN from standby and hibernation (Magic Packet and

Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet

only)

PXE 2.1 Remote Boot

Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB

(802.3x, clause 30))

Comprehensive diagnostic and configuration software suite

Virtual Cable Doctor for Ethernet cable status

Interface PCI Express 1.1 x1 to fully support ASPM LOs/L1 and CLKREQ.

NOTE: Intel 82579 PCIe interface is not PCIe compliant. It operates

at half of PCIe specification V1.1 (2.5GT/S) speed.

NIC Device Driver Name Intel 82579LM/82579V Ethernet Network Connection



Technical Specifications – Networking

HP lt4132 LTE/HSPA+ 4G Mobile Broadband Module

Technology/Operating

LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3) MHz,

850 (Band 5), 2600 (Band 7), 900 (Band 8) MHz,

800 (Band 20), 700 (Band 28) MHz.

HSPA+: 2100 (Band 1), 1900 (Band 2), 850 (Band 5), 900 (Band 8) MHz E-GPRS: 1900 (Band 2), 1800 (Band 3), 850 (Band 5), 900 (Band 8) MHz

Wireless protocol

standards

bands

3GPP Release 10 LTE Specification CAT.4, 20MHz BW

WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification E-GPRS: Class B, Multi-slot class 12, coding schemes CS1 - CS4

and MSC1 - MSC9

GPS Standalone, A-GPS (MS-B and LTO)

GPS bands 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz

Maximum data rates LTE: 150 Mbps (Download), 50 Mbps (Upload)

DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload) EDGE: 236.8 kbps (Download), 236.8 kbps (Upload) GPRS: 85.6 kbps(Download), 85.6 kbps (Upload)

Maximum output power

LTE: 23 dBm HSPA+: 23.5 dBm

E-GPRS 1900/1800: 26 dBm E-GPRS 900/850: 27 dBm GPRS 1900/1800: 29.5 dBm GPRS 900/850: 32.5 dBm

Maximum power consumption

LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average) E-GPRS: 2,600 mA (peak); 500 mA (average)

Form Factor M.2, 3042-S3 Key B

Weight 6 g

Dimensions 42 x 30 x 2.3 mm

(Length x Width x Thickness)

* Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

HP hs3210 HSPA+ Mobile Broadband Module*

Technology/Operating

HSPA+: 2100 (Band1), 1900 (Band 2), 850 (Band 5), 900 (Band 8) MHz E-GPRS: 1900 (Band 2), 1800 (Band 3), 850 MHz (Band 5), 900 (Band 8) MHz

Wireless protocol

WCDMA R99, 3GPP Release 5, 6 and 7 UMTS Specification

standards

bands

E-GPRS: Class B, Multi-slot class 33, coding schemes CS1 - CS4 and MSC1 - MSC9

Maximum data rates HSPA+: 21.6 Mbps (Download), 5.76 Mbps (Upload)

E-GPRS: 296 kbps (Download), 236.8 kbps (Upload) GPRS: 107 kbps (Download), 85.6 kbps (Upload)

Maximum output power HSPA+: 24 dBm

E-GPRS 1800/1900: 26 dBm E-GPRS 850/900: 27 dBm



Technical Specifications – Networking

GPRS 1800/1900: 30 dBm GPRS 850/900: 33 dBm

Maximum powerHSPA+: 1,100 mA (peak); 800 mA (average)consumptionE-GPRS: 2,800 mA (peak); 700 mA (average)

Form Factor M.2, 2242-S3 Key B

Weight 6 g

Dimensions 1.65 x 8.66 x 0.09 in (42 x 22 x 2.38 mm)

(Length x Width x Thickness)

* Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors.

HP lt4120 Qualcomm® Snapdragon™ X5 LTE Mobile Broadband Module

Technology/Operating

LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3),

bands

1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 17 lower),

800 (Band 20), 700 (Band 28).

HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4),

850 (Band 5), 900 (Band 8) MHz

EV-DO: 850 (BC0), 1900 (BC1) MHz (Only work with Verizon network) E-GPRS: 1900 (Band 2), 1800 (Band 3), 850 (Band 5), 900 (Band 8)

MHz

Wireless protocol

standards

3GPP Release 10 LTE Specification CAT.4, 20MHz BW WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

1xEVDO Release O, A and B.

E-GPRS: Class B, Multi-slot class 12, coding schemes CS1 - CS4

and MSC1 - MSC9

GPS Standalone, A-GPS (MS-A, MS-B and XTRA)

GPS bands 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz

Maximum data rates LTE: 150 Mbps (Download), 50 Mbps (Upload)

DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21 Mbps (Download), 5.76 Mbps (Upload)

CDMA 1xRTT: 153.6 kbps (Download), 153.6 kbps (Upload) EVDO Rel.A: 3.1 Mbps (Download), 1.8 Mbps (Upload) EVDO Rel.B: 14.7 Mbps (Download), 5.4 Mbps (Upload) EDGE: 236.8 kbps (Download), 236.8 kbps (Upload) GPRS: 85.6 kbps(Download), 85.6 kbps (Upload)

Maximum output power LTE: 23 dBm

HSPA+: 23.5 dBm 1xRTT/EVDO: 24dBm E-GPRS 1900/1800: 26 dBm E-GPRS 900/850: 27 dBm GPRS 1900/1800: 29.5 dBm GPRS 900/850: 32.5 dBm

Maximum power consumption

LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)

1xRTT/EVD0: 1,000 mA (peak); 700 mA (average)

E-GPRS: 2,800 mA (peak); 500 mA (average)

Form Factor M.2, 3042-S3 Key B

Weight 6.2 g



Technical Specifications - Networking

Dimensions

42 x 30 x 2.3 mm

(Length x Width x Thickness)

Intel® Dual Band					
Wireless-AC 8265 802.11					
AC/a/b/g/n (2x2) WiFi +					
Bluetooth® 4.2 Combo					
Adaptor* (vPro)					

Wireless LAN Standards IEEE 802.11a
IEEE 802.11b
IEEE 802.11g
IEEE 802.11n
IEEE 802.11n

Wi-Fi certified

802.11b/q/n

Interoperability

Frequency Band

2.402 - 2.482 GHz

Note: The FCC has declared as of January 1, 2015 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise

disable those channels

802.11a 4.9 - 4.95 GHz (Japan) 5.15 - 5.25 GHz

5.25 - 5.35 GHz 5.47 - 5.725 GHz 5.825 - 5.850 GHz

Note: Indonesia only supports 5.725 - 5.825 GHz

(CH149 - CH161)

Data Rates

- 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
- 802.11b: 1, 2, 5.5, 11 Mbps
- 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
- 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
- 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)

Modulation

Direct Sequence Spread Spectrum CCK, BPSK, QPSK, 16-QAM, 64-QAM, 256-QAM

Security¹

- IEEE and Wi-Fi compliant 64 / 128 bit WEP encryption for
- a/b/g mode only
- AES-CCMP: 128 bit in hardware
- 802.1x authentication
- WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
- WPA2 certification
- IEEE 802.11i
- Cisco Certified Extensions, all versions through CCX4 and CCX Lite
- WAPI

Network Architecture

Models Roaming

Output Power²

Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

IEEE 802.11 compliant roaming between band Access Points

- 802.11b: +16dBm minimum
- 802.11g: +14dBm minimum
- 802.11a: +14dBm minimum
- 802.11n HT20(2.4GHz): +13dBm minimum
- 802.11n HT40(2.4GHz): +13dBm minimum



Technical Specifications – Networking

802.11n HT20(5GHz): +12dBm minimum
 802.11n HT40(5GHz): +12dBm minimum

Power Consumption Transmit: 2.0 Watts (max)

Receive: 1.6 Watts (max)

Idle mode (PSP): 180 mW (WLAN Associated)
Idle mode: 50 mW (WLAN unassociated)
Connect Standby: 10mW (WLAN + BT)

Radio disabled: 5 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity³ 802.11b, 1Mbps: -94dBm maximum

802.11b, 11Mbps: -86dBm maximum 802.11g, 6Mbps: -88dBm maximum 802.11g, 54Mbps: -74dBm maximum 802.11a, 6Mbps: -88dBm maximum 802.11a, 54Mbps: -74dBm maximum 802.11n, MCS07: -69dBm maximum 802.11n, MCS15: -66dBm maximum 802.11ac, 1SS, MCS-0: -86dBm maximum 802.11ac, 2SS, MCS-9: -61dBm maximum 802.11ac, 2SS, MCS-9: -58dBm maximum

Antenna Type High efficiency antenna with spatial diversity, mounted in the

display enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard

Dimensions Type 2230 : 2.3 x 22.0 x 30.0 mm

0r

Type 1630: 2.3 x 16.0 x 30.0 mm

Weight Type 2230: 2.8g

0r

Type 1630: 2g

Operating Voltage 3.3v +/- 9%

TemperatureOperating 14° to 158° F (-10° to 70° C)
Non-operating -40° to 176° F (-40° to 80° C)

Humidity Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

Altitude Operating Non- 0 to 10,000 ft (3,048 m)

operating 0 to 50,000 ft (15,240 m)

LED Activity LED Amber – Radio OFF; LED White – Radio ON



Technical Specifications – Networking

HP Integrated Module with Bluetooth® 4.2 Wireless Technology

Bluetooth® Specification 4.2 Compliant

> **Frequency Band** 2402 to 2480 MHz

Number of Available Channels Legacy: 0~79 (1 MHz/CH)

BLE: 0~39 (2 MHz/CH)

Data Rates and Throughput Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps

BLE: 1 Mbps data rate; throughput up to 0.2 Mbps

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps,

voice channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth

device with a maximum transmit power of +4 dBm for BR and EDR

Modulation 0.01% BER 0.001% BER **Receiver Sensitivity**

GFSK -80 dBm -70 dBm π/4-DQPSK -80 dBm -70 dBm 8DPSK -80 dBm -70 dBm

Power Consumption Peak (Tx) 330 mW

> Peak (Rx) 230 mW Selective Suspend 17 mW

Antenna Internally integrated within module

Legacy Up to 33 ft (10 m) Range

BLE Up to 99 ft (30 m)

Electrical Interface USB 2.0 compliant

Bluetooth® Software Supported Microsoft Windows Bluetooth Software

Link Topology Point to Point, Multipoint Pico Nets up to 7 slaves Security Full support of Bluetooth Security Provisions **Power Management** Microsoft Windows ACPI, and USB Bus Support

Certifications

Self-configurable to optimize power conservation in all operating

modes, including Standby, Hold, Park, and Sniff

Security All necessary regulatory approvals for supported countries,

including:

FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power management ETS 300 328, ETS 300 826 certificactions Low Voltage Directive IEC950

UL, CSA, and CE Mark

Certifications Serial Port Profile (SPP)1

Bluetooth® Profiles Supported Service Discovery Application Profile (SDAP)

Dial-Up Networking (DUN)1,2

Generic Object Exchange Profile (GOEP)1,2

Object Push Profile (OPP)1,2

Hard Copy Cable Replacement (HCRP)1,2 Personal Area Networking Profile (PAN)1,2 Human Interface Device Profile (HID)1,2

Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP) Audio Video Remote Control Profile (AVRCP)



Technical Specifications – Networking

Bluetooth® V4.2 support feature

V4.2: ESR8 compliant, LE Secure Connection – Basic.

- 1. Check latest software/driver release for updates on supported security features.
- 2. Maximum output power may vary by country according to local regulations.
- 3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CCK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

WLAN supplier's client utility is required for Cisco Compatible Extensions support with Microsoft Windows XP. WLAN may also be compatible with certain third-party software supplicants. WLAN supplier IHV extensions required for Cisco Compatible Extensions support for Microsoft Windows Vista.



Technical Specifications – Networking

Intel® Dual Band Wireless-AC 8265 802.11 AC/a/b/g/n (2x2) WiFi + Bluetooth® 4.2 Combo Adaptor* (non-vPro) Wireless LAN Standards

IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac

Interoperability
Frequency Band

Wi-Fi certified 802.11b/g/n

2.402 - 2.482 GHz

Note: The FCC has declared as of January 1, 2015 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels

802.11a

- 4.9 4.95 GHz (Japan)
- 5.15 5.25 GHz
- 5.25 5.35 GHz
- 5.47 5.725 GHz
- 5.825 5.850 GHz

Note: Indonesia only supports 5.725 - 5.825 GHz (CH149 - CH161)

Antenna Structure

Data Rates

2 transmit; 2 receive (2x2)

802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps

802.11b: 1, 2, 5.5, 11 Mbps

802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps

802.11n: card will support rates for NSS=1 and NSS=2 for RX and TX for 20 and 40 MHz channels. Short and long guard interval shall be supported.

802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and

80MHz)

Modulation

Direct Sequence Spread Spectrum

BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

Security¹

- IEEE and Wi-Fi compliant 64 / 128 bit WEP encryption for a/b/g mode only
- AES-CCMP: 128 bit in hardware
- 802.1x authentication
- WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
- WPA2 certification
- IEEE 802.11i
- Cisco Certified Extensions, all versions through CCX4 and CCX Lite
- WAPI

Network Architecture

Models

Roaming

Output Power²

Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

IEEE 802.11 compliant roaming between access points

- 802.11b: +16dBm minimum
- 802.11g: +14dBm minimum
- 802.11a: +14dBm minimum



Technical Specifications – Networking

802.11n HT20(2.4GHz): +13dBm minimum 802.11n HT40(2.4GHz): +13dBm minimum 802.11n HT20(5GHz): +12dBm minimum 802.11n HT40(5GHz): +12dBm minimum 802.11ac 80MHz(5GHz): +11dBm minimum

Power Consumption Transmit: 2.0 W (max)

Receive: 1.6 W (max)

Idle mode (PSP): 180 mW (WLAN Associated) Idle mode: 60 mW (WLAN unassociated)

Radio disabled: 30 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

802.11g:-90 dBm (6 Mbps), -89 dBm (9 Mbps), -87 dBm (12 Mbps), -Receiver Sensitivity³

85 dBm (18 Mbps), -82 dBm (24 Mbps), -79 dBm (36 Mbps), -76 dBm

(48 Mbps), -74 dBm (54 Mbps)

802.11b:-95 dBm (1 Mbps), -93 dBm (2 Mbps), -91 dBm (5.5 Mbps), -

88 dBm (11 Mbps)

802.11g:-90 dBm (6 Mbps), -89 dBm (9 Mbps), -87 dBm (12 Mbps), -85 dBm (18 Mbps), -82 dBm (24 Mbps), -79 dBm (36 Mbps), -76 dBm

(48 Mbps), -74 dBm (54 Mbps)

802.11n:-69 dBm (150 Mbps), -66 dBm (300 Mbps)

High efficiency antenna with spatial diversity, mounted in the Antenna type

display enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the

card to support WLAN MIMO communications and Bluetooth

communications

Form Factor PCI-Express Half-MiniCard

Dimensions 0.134 x 1.06 x 1.18 in (3.4 x 26.8 x 30 mm)

Weight 3.1q

Operating Voltage 3.3v +/- 9%

14° to 158° F (-10° to 70° C) Temperature Operating

> -40° to 176° F (-40° to 80° C) Non-operating

Humidity Operating 10% to 90% (non-condensing)

> Non-operating 5% to 95% (non-condensing)

Altitude Operating 0 to 10.000 ft. (3.048 m)

> Non-operating 0 to 50,000 ft. (15,240 m)

LED Amber - Radio OFF: LED White - Radio ON **LED Activity**

- 1. Check latest software/driver release for updates on supported security features.
- 2. Maximum output power may vary by country according to local regulations.
- 3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

HP Integrated Module with Bluetooth® 4.2 Wireless Technology

Bluetooth Specification 4.0+EDR Compliant **Frequency Band** 2402 to 2480 MHz

Number of Available Channels 79 (1 MHz) available channels

Data Rates and Throughput 3 Mbps data rate; throughput up to 2.17 Mbps



Technical Specifications – Networking

Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric or 1306.9 kbps symmetric

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth

device with a maximum transmit power of +4 dBm for BR and EDR

Receiver Sensitivity Better than -20 dBM at 0.1 % raw bit error rate

Power Consumption Peak (Tx) 330 mW

Peak (Rx) 230 mW

Selective Suspend 17 mW

Antenna Internally integrated within module

Range Up to 33 ft. (10 m)
Electrical Interface USB 2.0 compliant

Microsoft Windows Plug and Play compliant

Bluetooth® Software

Supported

Broadcom Bluetooth for Windows

Microsoft Windows Bluetooth Software

Link TopologyPoint to Point, Multipoint Pico Nets up to 7 slavesSecurityFull support of Bluetooth Security ProvisionsPower ManagementMicrosoft Windows ACPI, and USB Bus Support

Self-configurable to optimize power conservation in all operating

modes, including Standby, Hold, Park, and Sniff

Certifications All necessary regulatory approvals for supported countries,

including:

FCC (47 CFR) Part 15C, Section 15.247 & 15.249

ETS 300 328, ETS 300 826 Low Voltage Directive IEC950

UL, CSA, and CE Mark

Bluetooth® Profiles Supported Serial Port Profile (SPP)¹

Service Discovery Application Profile (SDAP)

Dial-Up Networking (DUN)1,2

Generic Object Exchange Profile (GOEP)1,2

Object Push Profile (OPP)^{1,2} File Transfer Profile (FTP) Synchronization Profile (SYNC)

Hard Copy Cable Replacement (HCRP)^{1,2} Personal Area Networking Profile (PAN)^{1,2} Human Interface Device Profile (HID)^{1,2}

FAX Profile (FAX)

Basic Imaging Profile (BIP)² Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

- 1. Indicates the profile is supported by Microsoft Windows XP SP2
- 2. Indicates the profile is part of Windows Vista
- * Wireless access point and internet service required. Availability of public wireless access points limited.



Technical Specifications – Networking

Intel® Dual Band Wireless - Wireless LAN IEEE 802.11a AC 3168 802.11 ac (1x1) **Standards** IEEE 802.11b WiFi and Bluetooth® 4.2 IEEE 802.11q Combo Adapter (non-vPro) IEEE 802.11n IEEE 802.11ac

Interoperability Wi-Fi certified **Frequency Band** 802.11b/q/n

• 2.402 – 2.482 GHz

Note: The FCC has declared as of January 1, 2015 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

802.11a/n

- 4.9 4.95 GHz (Japan)
- 5.15 5.25 GHz
- 5.25 5.35 GHz
- 5.47 5.725 GHz
- 5.825 5.850 GHz

Note: Indonesia only supports 5.725 - 5.825 GHz (CH149 - CH161)

Data Rates

- 802.11b: 1, 2, 5.5, 11 Mbps
- 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
- 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
- 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
- 802.11ac: MCS0 ~ MCS7, (1SS) (20MHz, 40MHz, and 80MHz)

Modulation

Direct Sequence Spread Spectrum

BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

Security¹

- IEEE and Wi-Fi compliant 64 / 128 bit WEP encryption for a/b/g mode only
- AES-CCMP: 128 bit in hardware
- 802.1x authentication
- WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
- WPA2 certification
- IEEE 802.11i
- Cisco Certified Extensions, all versions through CCX4 and CCX Lite

Network Architecture Ad-hoc (Peer to Peer)

Models

Infrastructure (Access Point Required)

Roaming

IEEE 802.11 compliant roaming between access points

Output Power²

- 802.11b: +16dBm minimum
- 802.11g: +14dBm minimum
- 802.11a: +14dBm minimum
- 802.11n HT20(2.4GHz): +13dBm minimum
- 802.11n HT40(2.4GHz): +13dBm minimum
- 802.11n HT20(5GHz): +12dBm minimum
- 802.11n HT40(5GHz): +12dBm minimum
- 802.11ac 80MHz(5GHz): +11dBm minimum

Power Consumption Transmit: 2.0 W (max)



Technical Specifications – Networking

Receive: 1.6 W (max)

Idle mode (PSP): 180 mW (WLAN Associated)
Idle mode: 60 mW (WLAN unassociated)

Radio disabled: 30 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity³ 802.11b, 1Mbps: -94dBm maximum

802.11b, 11Mbps: -86dBm maximum 802.11g, 6Mbps: -88dBm maximum 802.11g, 54Mbps: -74dBm maximum 802.11a, 6Mbps: -86dBm maximum 802.11a, 54Mbps: -72dBm maximum 802.11n, MCS07: -69dBm maximum 802.11n, MCS15: -66dBm maximum 802.11ac, 1SS, MCS-0: -86dBm maximum 802.11ac, 2SS, MCS-0: -83dBm maximum

Antenna type High efficiency antenna with spatial diversity, mounted in the display

802.11ac, 2SS, MCS-9: -58dBm maximum

enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard

Dimensions Type 2230 : 2.3 x 22.0 x 30.0 mm

Or

Type 1630: 2.3 x 16.0 x 30.0 mm

Weight Type 2230 : 2.8g

0r

Type 1630: 2g

Operating Voltage 3.3v +/- 9%

Temperature Operating 14° to 158° F (-10° to 70° C)

Non-operating 40° to 176° F (-40° to 80° C)

Humidity Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)
Operating 0 to 10 000 ft (3 048 m)

 Altitude
 Operating
 0 to 10,000 ft (3,048 m)

 Non-operating
 0 to 50,000 ft (15,240 m)

Near Field Communications (NFC)

Controller HP Module with NXP NFC Controller NPC100

• Windows 8, Proximity Events

Windows 7, PC/SC

NFC Forum Compliant

Near Field Communications Controller

Dimensions Module 25 mm by 10 mm by 2.0 mm (L x W x H)

Chipset NPC100 System interface I2C

NFC RF standards standards ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092

ECMA-340 NFCIP-1 Target and Initiator ECMA-320 NFCIP-2

Technical Specifications - Networking

NFC Forum Support

Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2

Tag

(PCD-VCD) Mode(1) ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 MIFARE Reader

1K MIFARE 4K MIFARE DESFire FeliCa Jewel and Topaz cards

Card Emulation (PICC-VICC)

Mode¹ ISO/IEC 14443 A ISO/IEC 14443 B and B' MIFARE FeliCa

13.56 MHz **Frequency**

NFC Modes Supported Reader/Writer, Peer-to-Peer **Raw RF Data Rates** 106, 212, 424, 848 kbps

Operating temperature 0°C to 70°C

Storage temperature -20°C to 125°C

Humidity

10-90% operating 5-95% non-operating

Supply Operating

2.97 to 5.5 Volts

voltage

I/O Voltage 1.8V or 3.3V

Power Consumption Booster enable, **VBAT= 3.3V,**

> VCC BOOST = 5V)**Mode Power** Consumption,

Typical² Polling 7.3 mA Detected Test Tag Type 1 Total 283.8 mA Net Module 236.8 mA Detected Test Tag Type 2 Total 288.8 mA Net Module 241.8 mA Detected Test Tag Type 3 Total 287.7 mA Net Module 240.7 mA Detected Test Tag Type 4 Total 282.3 mA Net Module

235.3 mA

Antenna connector

0.5mm pitch, 7 connector FPC. Antenna matching is external to module.

Notes

1. With application or UICC support

2. Actual Power Consumption is dependent on NFC antenna and matching circuit and on the particular polling sequence and period configured.

Technical Specifications – Audio

AUDIO/MULTIMEDIA – BANG & OLUFSEN

Hardware Implementation Conexant CX7501

> **Function Key** Volume up, volume down, and mute

Volume Controls

Line In/Line Out Yes, via dock Headphone/Microphone in Yes combo jack

Integrated Microphone Yes, dual digital microphone array when equipped with optional webcam

Audio Output Quality 20 Hz - 20 kHz **Frequency Response**

> Signal to Noise Ratio >85 dB **Total Harmonic Distortion** 0.01% **Noise Floor** -110 dB Play/Record Sampling Rate(s) 8 kHz - 48kHz DAC 16, 20 or 24-bit

ADC 16,20-bit

Integrated Stereo

Power Rating 2 Watts **Speakers** 4 Ohms **Impedance**



Technical Specifications – Power

POWER

HP 65W Smart AC Adapter

Dimensions 107.0x47.0x30.0mm Weight unit: 250g +/- 10g Input 90 to 265 VAC

> **Input Efficiency** 88.0 % at 115 Vac and 89.0 % at 230 Vac

Input frequency 47 to 63 Hz

range

Input AC current 1.7 A at 90 Vac

Output **Output power** 65W

> DC output 19.5V

Hold-up time 5 ms at 115 Vac input

<11.0A Output current limit

AC Connector (Ac Inlet) C6 (3pin/with grounded, with Smart ID DC connector)

AC Connector (Ac Inlet) Environmental Design

Operating temperature

32° to 95° F (0° to 35° C)

Non-operating

(storage) temperature -4° to 185° F (-20° to 85° C)

Altitude 0 to 16,400 ft (0 to 5,000 m)

Humidity 20% to 95% Storage Humidity 10% to 95%

EMI and Safety Certifications *CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition.

HP 65W Smart AC Adapter EM **Dimensions** 102.0x55.0x30.0mm Weight unit: 350g +/- 10g 90 to 265 VAC Input

> **Input Efficiency** 87.0% min at 115 VAC and 230Vac

Input frequency

range

47 to 63 Hz

Input AC current 1.7 A at 90 VAC

Output **Output power** 65W

DC output 19.5V

Hold-up time 5 ms at 115 Vac input

Output current limit <11.0A

AC Connector (Ac Inlet) C6 (3pin/with grounded, with Smart ID DC connector)

Technical Specifications – Power

AC Connector (Ac Inlet)

Environmental Design

Operating
temperature

32° to 95° F (0° to 35° C)

Non-operating

(storage) -4° to 185° F (-20° to 85° C)

temperature

Altitude 0 to 16,400 ft (0 to 5,000 m)

Humidity 20% to 95% **Storage Humidity** 10% to 95%

EMI and Safety Certifications *CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

* MTBF - over 200,000 hours at 25°C ambient condition.

HP 65W Travel AC Adapter

 Dimensions
 120.0x57.6x16.7mm

 Weight
 unit: 250g +/- 10g

Input Input Efficiency 88.0 % at 115 Vac and 89.0 % at 230Vac

Input frequency range 47 to 63 Hz
Input AC current 1.7 A at 90 Vac

Output Output power 65W

DC output 19.5V/5V

Hold-up time 5 ms at 115 Vac input

Output current limit <11.0A

DC Plug 4.5mm/7.4mm tips

Environmental Design Operating 32° to 95° F (0° to 35° C)

temperature

Non-operating (storage)

temperature ⁻⁴

-4° to 185° F (-20° to 85° C)

Altitude 0 to 16,400 ft (0 to 5,000 m)

Humidity 20% to 95% **Storage Humidity** 10% to 95%

EMI and Safety Certifications *CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC

Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

* MTBF - over 200,000 hours at 25°C ambient condition.



Technical Specifications – Power

HP Long Life 3-cell Dimensions (H x W x L) Polymer Battery (51WHr) Weight

6.8mm x 102.8mm x 198mm

235 q

Cells/Type 3cell Lithium-Ion Polymer cell / 506480 Energy 11.55V

Voltage Amp-hour capacity 4420mAh

> Watt-hour capacity 51wh

Temperature Operating (Charging) 32° to 113° F (0° to 45° C)

> Operating (Discharging) 14° to 140° F(-10° to 60° C)

Fuel Gauge LED No

1000 cycles > 65% (at 23°C) Warranty

Optional Travel Battery

Available

ENVIRONMENTAL DATA

Eco-Label Certifications & declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- **US ENERGY STAR®**
- EPEAT[®] Gold registered in the United States. See http://www.epeat.net for registration status in your country. Search keyword *generator* on HP's 3rd party option store for solar energy accessory at http://www.hp.com/go/options.

System Configuration

The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook".

Energy Consumption (in accordance with US **ENERGY STAR® test method)**

Normal Operation (Short idle) Normal Operation (Long idle) Sleep Off

115VAC, 60Hz	230VAC. 50Hz	100VAC. 50Hz
7.38 W	7.86 W	7.56 W
3.58 W	4.01 W	3.91 W
0.88 W	0.94 W	0.9 W
0.48 W	0.53 W	0.49 W

Note:

Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

Heat Dissipation*

Normal Operation (Short idle) Normal Operation (Long idle) Sleep Off

115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
25 BTU/hr	27 BTU/hr	26 BTU/hr
12 BTU/hr	14 BTU/hr	13 BTU/hr
3 BTU/hr	3 BTU/hr	3 BTU/hr
2 BTU/hr	2 BTU/hr	2 BTU/hr

*NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.



Options and Accessories (sold separately and availability may vary by country)

Declared Noise Emissions		
(in accordance with		
ISO 7779 and ISO 9296)		
Typically Configured – Idle		
Fixed Disk – Random writes		
Longevity and Upgrading		

Sound Power (L _{WAd} , bels)	Sound Pressure (L _{pAm} , decibels)
2.6	16
3.7	22

This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:

- 3 USB ports
- 1 PC card slot (type I/II)
- 1 ExpressCard/54 slot
- 1 IEEE 1394 Port
- 2 SODIMM memory slots
- · Optional expansion base docking station
- 1 multi-bay II storage port
- Interchangeable HDD??

Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.

Batteries

This battery(s) in this product comply with EU Directive 2006/66/EC

Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight

Battery description: CR2032 (coin cell)

Battery type: Lithium

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT) standard at the gold level, see www.epeat.net
- Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.
- This product contains 9.0% post-consumer recycled plastic (by wt.)
- This product is 96.9% recycle-able when properly disposed of at end of life.

Pac	kagin	ıg Ma	iteri	ials

Material Usage

External:	PAPER/Corrugated	357 g
Internal:	PLASTIC/Polyethylene Expanded - EPE	76 g
	PLASTIC/Polypropylene - PP	4 g
	PLASTIC/Polyethylene low density - LDPE	15 g

The plastic packaging material contains at least 50% recycled content.

The corrugated paper packaging materials contains at least 70% recycled content.

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):

Options and Accessories (sold separately and availability may vary by country)

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) except for wires and cables, has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging Usage

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.



Options and Accessories (sold separately and availability may vary by country)

HP, Inc. Corporate
Environmental Information

For more information about HP's commitment to the environment:

Global Citizenship Report

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

Eco-label certifications

http://www8.hp.com/us/en/hp-information/environment/ecolabels.html

ISO 14001 certificates:

http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842

and

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

Country of Origin

China



Options and Accessories (sold separately and availability may vary by country)

Туре	Description	Part #
Memory	HP 4GB DDR4-2400 SODIMM (Core processors only)	Z4Y84AA
	HP 16GB DDR4-2400 SODIMM (Core processors only)	Z4Y86AA
Cases	HP Executive 15.6 Black Top Load	P6N18AA
	HP Business Case (up to 15.6")	H5M92AA
	HP Essential Top Load Case (up to 15.6")	H2W17AA
Docking	HP UltraSlim Docking Station	D9Y32AA
Ducking	HP 2013 UltraSlim Docking Station TAA (US only)	E5C22AV#ABA
	HP Executive Travel Hub	TOK29AA
	HP Travel Hub	TOK23AA
	HP 3005pr USB 3.0 Port Replicator w/ USB-C Adapter	Y4H06AA
	HP Display and Notebook Stand II	E8G00AA#xxx
	HP USB-Type C™ Elite Dock	X7W54AA
	HP UltraSlim Docking Station	D9Y32AA
	The Ottrastilli Docking Station	DOTOZAK
Input/Output -	HP Comfort Grip Mouse	H2L63AA
Mice	HP 3-Button Laser Mouse	H4B81AA#xxx
	HP Ultra Mobile Wireless Mouse	H6F25AA#xxx
	HP X4000 Bluetooth Mouse	H3T50AA#xxx
	HP Slim Bluetooth Mouse	F3J92AA#xxx
	HP Ultrathin Wireless Mouse	L9V78AA
	HP USB Travel Mouse	G1K28AA#xxx
	HP Slim Wireless Keyboard and Mouse	T6L04AA#xxx
	HP USB Essential Keyboard and Mouse	H6L29AA#xxx
	HP Slim USB Keyboard and Mouse	T6T83AA
	HP Wireless (Link-5) Keyboard	T6U20AA#xxx
	HP Comfort Grip Wireless Mouse	H2L63AA
Power Adapters	HP 65W Slim A/C Adapter w/USB	H6Y82AA
	HP 90W Slim A/C Adapter w/USB	H6Y83AA
	HP 90W Slim Auto Combo AC Adapter w/USB	H6Y84AA
	HP 65W Smart AC Adapter	H6Y89AA
	HP 90W Smart AC Adapter	H6Y90AA
	HP 65W Slim AC Adapter	H6Y82AA
Battery	HP TA03XL Rechargeable Battery	1FN06AA
		II HOUAN
Adapters	HP USB-C™ to VGA Adapter	N9K76AA
	HP USB-C to USB 3.0	N2Z63AA
	HP USB-C to USB Hub	Z6A00AA
	UDUCD CIMA DisplayDoutin Adout	Nove
	HP USB-C™ to DisplayPort™ Adapter	N9K78AA



Options and Accessories (sold separately and availability may vary by country)
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Options and Ac	cessories (Solu Separately and availability may vary by Country	y)
	HP USB-C™ to DisplayPort™ Adapter	N9K78AA
	HP HDMI to DVI adapter	F5A28AA
	DisplayPort™ to DVI Adapter	F7W96AA
	DisplayPort™ to VGA	F7W97AA
	DisplayPort™ to HDMI 1.4 Adapter	F3W43AA
Displays	HP Z24n G2 24-inch Display	1JS09A8
Wireless	HP lt4120 LTE/EVDO/HSPA+ Gobi™ 4G Mobile Broadband Module	TBD
Collaboration	HP UC Conferencing Keyboard	K8P74AA#xxx
	HP UC Speaker Phone	K7V16AA
	HP UC Wired Headset	K7V17AA
	HP UC Mono Wireless Headset	W3K08AA
	HP UC Duo Wireless Headset	W3K09AA
	HP Stereo 3.5mm Headset	T1A66AA
	HP Stereo USB Headset	T1A67AA
_	HP External USB DVDRW Drive	F2B56AA
Storage	HP 500GB 7200rpm HDD	F3B97AA
	HP 256GB M2 NVME PCIe SSD (2280)	V3K66AA
	HP 512GB M2 NVME PCIe SSD (2280)	V3K67AA
Security	HP Dual Head Cable Lock (Non-Master key)	T1A64AA
	HP Dual Head Cable Lock (Master Key)	T1A65AA
	HP 15.6" Notebook PC Privacy Filter (non-touch)	J7H71AA
	HP Docking Station Cable Lock	AU656AA#XXX
	HP Essential Combination Lock	TOY16AA
	HP Combination Lock	TOY15AA
	HP Keyed Cable Lock	TOY14AA
	HP 15'6 Privacy Filter (touch panel)	V8Z58AA#xxx
Care Packs	(for 1 year platforms)	UC282E
	(for 3 year platforms)	UC279E

NOTE: External power supplies, power cords, cables and peripherals are not low halogen. Service parts obtained after purchase may not be low halogen.

Summary of Changes

Date of change:	Version History:		Description of change:
February 15, 2018	From v1 to v2	Change	Environmental data updated
February 23, 2018	From v2 to v3	Added	Dock, case, mouse, adapter, display and care packs added to options section
March 1, 2018	From v3 to v4	Added	Battery note on power supply section



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